

ABSTRACT

The objective of the invention is to prevent electrostatic destruction of semiconductor chips during resin molding. With the semiconductor device manufacturing method, a substrate 400 that includes on the surface multiple semiconductor chips 410 and liquid resin 434 supplied to multiple semiconductor devices is supported by an electrically insulated lower die 200. An upper die 110 in which multiple shape-forming parts (cavities) 112 are formed is pressed against lower die 200 through the medium of a polymer release film 300, and liquid resin 434 on the substrate is molded.